



CH03-AB - SIM CARD HOLDER WITH SWITCH 6 PINS, SLID IN TYPE, WITH HALF METAL COVER

FEATURES

1. GENERAL CHARACTERISTICS

DIMENSIONS: 15.85L x 16.50W x 3.00H mm  
 WEIGHT: APPROX. 0.70g  
 CONTACT PRINCIPLE: FRICTION TECHNOLOGY  
 OPERATING POSITION: SHAFT UP / DOWN / HORIZONTAL  
 MOUNTING SYSTEM: SMT TYPE WITHOUT POST  
 DURABILITY: 10,000 CYCLES MIN.

2. MECHANICAL CHARACTERISTICS

INSULATION MATERIAL: LCP+30% G.F, UL 94V-0  
 CONTACT MATERIAL: PHOSPHER BRONZE  
 PLATING :

DATA CONTACTS -

GOLD FLASH ON CONTACT AREA OVER 50U" NICKEL  $\Delta$   
 GOLD FLASH ON SOLDER AREA (PCB SIDE) OVER 50U" NICKEL  $\Delta$   
 50U" NICKEL ON THE REST.  $\Delta$

CARD DETECTOR / SWITCH -

GOLD FLASH OVER 50U" NICKEL  $\Delta$

METAL SHELL MATERIAL: STAINLESS STEEL  $\Delta$

3. ELECTRICAL CHARACTERISTICS

CONTACT RESISTANCE: 50M OHMS TYP. 100M OHMS MAX.  
 INSULATION RESISTANCE: > 1000M OHMS / 500V DC  
 SWITCH TYPE: BLADE (Normally Open)  
 RATED CURRENT: 1A MAX.  
 RATED VOLTAGE: 50V MAX.  
 WITHSTANDING DIELECTRIC VOLTAGE: 50V AC R.M.S. FOR 1 MINUTE

4. SOLDERABILITY

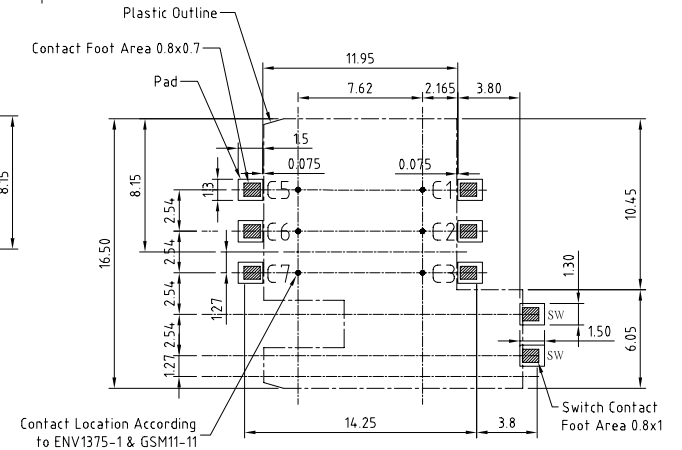
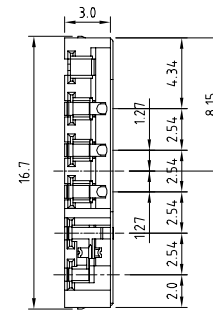
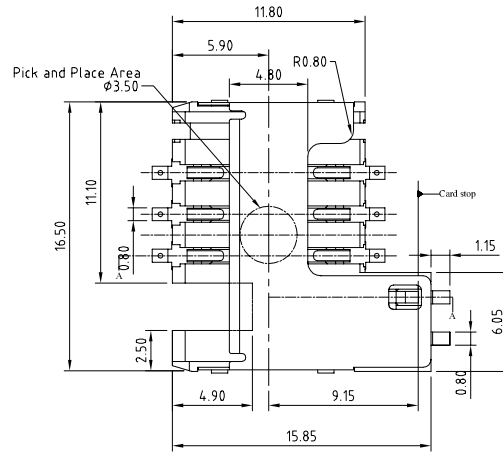
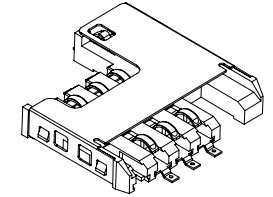
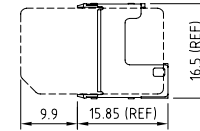
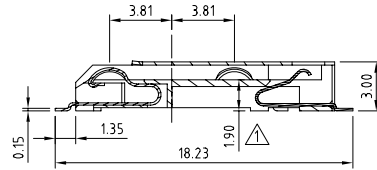
WAVE: NOT APPLICABLE  
 IR REFLOW: 260°C, 10 SEC. MAX.  $\Delta$   
 MANUAL SOLDERING: 360°C, 3 SEC. MAX.

5. ENVIRONMENTAL CHARACTERISTICS

OPERATING TEMPERATURE: -40°C ~ +85°C  
 OPERATING HUMIDITY: 10% ~ 95% RH  
 STORAGE TEMPERATURE: -40°C ~ +85°C  
 STORAGE HUMIDITY: 10% ~ 95% RH  
 THERMAL SHOCK: -40°C ~ +85°C, 5 CYCLES  
 DAMP HEAT: 40°C, 90% RH, 500HR  
 SALT-MIST: 35°C, 5% NaCl, 48HR

NOTES:

1. ACCEPTABLE SIM CARD SIZE SHOULD MEET GSM 11.11 SPECIFICATION REQUIREMENT.  $\Delta$



RECOMMENDED PCB LAYOUT

HOW TO ORDER



NO. OF CONTACTS

$\Delta$  PACKAGING OPTIONS

R = REEL  
 (700PCS/REEL)

|    |              |                         |
|----|--------------|-------------------------|
| 10 | 25/09/05-NYW | RELEASE                 |
| 11 | 27/09/06-NYW | ADD DIMENSION           |
| 12 | 05/10/06-NYW | AMEND R MAX TEMP        |
| 13 | 29/05/07-NYW | ADD NOTES 1             |
| 14 | 28/09/07-NYW | REMOVE PACK OPTION TUBE |
| 15 | 14/06/08-NYW | ADD ELECTRICAL SPEC     |
| 16 | 28/04/09-PN  | PACKAGING DRAWING AMEND |
| 17 | 25/07/09-NYW | AMEND PLATING SPEC      |

|                  |                          |  |                      |
|------------------|--------------------------|--|----------------------|
| Scale: 3:1       | THIRD ANGLE              | Unstated Tolerances:<br>0 Dec Places<br>1 Dec Places<br>2 Dec Places<br>3 Dec Places | Material<br>SEE NOTE |
| Drawn: NYW       |                          |  |                      |
| App'd: XXXX      | Title: SIM CARD ACCEPTOR |  | NOT TO SCALE         |
| Date: 25 OCT '10 | Revision: 1.7            |  | Unit: mm             |

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|   |
|---|
| Type: CH03-AB   |
| CH03-AB   |
| Drawing Number:   |
| Sheet 1 of 2  |
| Drawing C <input type="radio"/> E and O <input type="radio"/> |